



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I ² C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	224 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 24x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-UFQFN Exposed Pad
Supplier Device Package	28-UQFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf15354-e-mv

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

2.0 GUIDELINES FOR GETTING STARTED WITH PIC16(L)F15354/55 MICROCONTROLLERS

2.1 Basic Connection Requirements

Getting started with the PIC16(L)F15354/55 family of 8bit microcontrollers requires attention to a minimal set of device pin connections before proceeding with development.

The following pins must always be connected:

All VDD and Vss pins (see Section 2.2 "Power Supply Pins")
MCLR pin (see Section 2.3 "Master Clear (MCLR) Pin")

These pins must also be connected if they are being used in the end application:

- PGC/PGD pins used for In-Circuit Serial Programming[™] (ICSP[™]) and debugging purposes (see **Section 2.4 "ICSP[™] Pins**")
- OSCI and OSCO pins when an external oscillator source is used

(see Section 2.5 "External Oscillator Pins")

Additionally, the following pins may be required:

• VREF+/VREF- pins are used when external voltage reference for analog modules is implemented

The minimum mandatory connections are shown in Figure 2-1.





2.2 Power Supply Pins

2.2.1 DECOUPLING CAPACITORS

The use of decoupling capacitors on every pair of power supply pins (VDD and VSS) is required.

Consider the following criteria when using decoupling capacitors:

- Value and type of capacitor: A 0.1 μ F (100 nF), 10-20V capacitor is recommended. The capacitor should be a low-ESR device, with a resonance frequency in the range of 200 MHz and higher. Ceramic capacitors are recommended.
- Placement on the printed circuit board: The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is no greater than 0.25 inch (6 mm).
- Handling high-frequency noise: If the board is experiencing high-frequency noise (upward of tens of MHz), add a second ceramic type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 μ F to 0.001 μ F. Place this second capacitor next to each primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible (e.g., 0.1 μ F in parallel with 0.001 μ F).
- Maximizing performance: On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB trace inductance.

2.2.2 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits, including microcontrollers, to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 μ F to 47 μ F.

000 = 1

REGISTER	9-6: OSCF	RQ: HFINTO	SC FREQUE	NCY SELEC	TION REGIS	TER	
U-0	U-0	U-0	U-0	U-0	R/W-q/q	R/W-q/q	R/W-q/q
	—	_	—		ŀ	HFFRQ<2:0> ⁽¹)
bit 7							bit 0
Legend:							
R = Readabl	e bit	W = Writable	bit	U = Unimpler	mented bit, read	d as '0'	
u = Bit is und	changed	x = Bit is unki	nown	-n/n = Value a	at POR and BO	R/Value at all	other Resets
'1' = Bit is set '0' = Bit is cleared							
bit 7-3	Unimplemer	nted: Read as '	0'				
bit 2-0	HFFRQ<2:0>	-: HFINTOSC I	Frequency Sele	ection bits			
	Nominal Free	<u>q (MHz):</u>					
	111 = Reserv	ved					
	110 = 32						
	101 = 16						
	100 = 12						
	011 = 8						
	010 = 4						
	001 = 2						

Note 1: When RSTOSC=110 (HFINTOSC 1 MHz), the HFFRQ bits will default to '010' upon Reset; when RSTOSC = 000 (HFINTOSC 32 MHz), the HFFRQ bits will default to '110' upon Reset.

11.0 POWER-SAVING OPERATION MODES

The purpose of the Power-Down modes is to reduce power consumption. There are three Power-Down modes: DOZE mode, IDLE mode, and SLEEP mode.

11.1 DOZE Mode

DOZE mode allows for power saving by reducing CPU operation and program memory (PFM) access, without affecting peripheral operation. DOZE mode differs from Sleep mode because the system oscillators continue to

operate, while only the CPU and PFM are affected. The reduced execution saves power by eliminating unnecessary operations within the CPU and memory.

When the Doze Enable (DOZEN) bit is set (DOZEN = 1), the CPU executes only one instruction cycle out of every N cycles as defined by the DOZE<2:0> bits of the CPUDOZE register. For example, if DOZE<2:0> = 100, the instruction cycle ratio is 1:32. The CPU and memory execute for one instruction cycle and then lay idle for 31 instruction cycles. During the unused cycles, the peripherals continue to operate at the system clock speed.



11.1.1 DOZE OPERATION

The Doze operation is illustrated in Figure 11-1. For this example:

- Doze enable (DOZEN) bit set (DOZEN = 1)
- DOZE<2:0> = 001 (1:4) ratio
- Recover-on-Interrupt (ROI) bit set (ROI = 1)

As with normal operation, the PFM fetches for the next instruction cycle. The Q-clocks to the peripherals continue throughout.

© 2016 Microchip Technology Inc.

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
OSCCON1	—		NOSC<2:0> NDIV<3:0>				108		
OSCCON2	—		COSC<2:0>	COSC<2:0> CDIV<3:0>					108
OSCCON3	CSWHOLD	SOSCPWR	_	ORDY	NOSCR	—	—	—	109
PCON0	STKOVF	STKUNF	WDTWV	RWDT	RMCLR	RI	POR	BOR	97
STATUS	—	—	_	TO	PD	Z	DC	С	29
WDTCON0	—	—			WDTPS<4:0	0>		SWDTEN	148
WDTCON1	—	V	VDTCS<2:0>		—	WI	NDOW<2:0>	>	149
WDTPSL				PSCN	T<7:0>				150
WDTPSH			PSCNT<15:8>						150
WDTTMR	_		WDTTM	R<4:0>		STATE	PSCNT	<17:16>	150

TABLE 12-3: SUMMARY OF REGISTERS ASSOCIATED WITH WATCHDOG TIMER

Legend: – = unimplemented locations read as '0'. Shaded cells are not used by Watchdog Timer.

TABLE 12-4: SUMMARY OF CONFIGURATION WORD WITH WATCHDOG TIMER

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
	13:8	—	-	FCMEN		CSWEN	-		CLKOUTEN	75
CONFIGT	7:0	_	F	RSTOSC<2:0	>	—	F	EXTOSC<2:0	>	75

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by Watchdog Timer.



FIGURE 17-1: INTERRUPT-ON-CHANGE BLOCK DIAGRAM (PORTB EXAMPLE)

ADC Clock P	eriod (TAD)	Device Frequency (Fosc)					
ADC Clock Source	ADCS<2:0>	32 MHz	20 MHz	16 MHz	8 MHz	4 MHz	1 MHz
Fosc/2	000	62.5ns ⁽²⁾	100 ns ⁽²⁾	125 ns ⁽²⁾	250 ns ⁽²⁾	500 ns ⁽²⁾	2.0 μs
Fosc/4	100	125 ns ⁽²⁾	200 ns ⁽²⁾	250 ns ⁽²⁾	500 ns ⁽²⁾	1.0 μs	4.0 μs
Fosc/8	001	0.5 μs ⁽²⁾	400 ns ⁽²⁾	0.5 μs ⁽²⁾	1.0 μs	2.0 μs	8.0 μs ⁽³⁾
Fosc/16	101	800 ns	800 ns	1.0 μs	2.0 μs	4.0 μs	16.0 μs ⁽³⁾
Fosc/32	010	1.0 μs	1.6 μs	2.0 μs	4.0 μs	8.0 μs ⁽³⁾	32.0 μs ⁽²⁾
Fosc/64	110	2.0 μs	3.2 μs	4.0 μs	8.0 μs ⁽³⁾	16.0 μs ⁽²⁾	64.0 μs ⁽²⁾
ADCRC	x11	1.0-6.0 μs ^(1,4)					

TABLE 20-1: ADC CLOCK PERIOD (TAD) Vs. DEVICE OPERATING FREQUENCIES

Legend: Shaded cells are outside of recommended range.

Note 1: See TAD parameter for ADCRC source typical TAD value.

2: These values violate the required TAD time.

3: Outside the recommended TAD time.

4: The ADC clock period (TAD) and total ADC conversion time can be minimized when the ADC clock is derived from the system clock FOSC. However, the ADCRC oscillator source must be used when conversions are to be performed with the device in Sleep mode.

FIGURE 20-2: ANALOG-TO-DIGITAL CONVERSION TAD CYCLES



REGISTER	22-2: NCO	ICLK: NCO1	INPUT CLO	CK CONTRO	L REGISTER		
R/W-0/0	R/W-0/0	R/W-0/0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
	N1PWS<2:0>(1	,2)	—		N1CK	S<3:0>	
bit 7							bit C
Legend:							
R = Readabl	e bit	W = Writable b	bit	U = Unimplen	nented bit, read	d as '0'	
u = Bit is und	changed	x = Bit is unkn	own	-n/n = Value a	at POR and BO	R/Value at all o	other Resets
'1' = Bit is se	et	'0' = Bit is clea	ired				
bit 4	111 = NCO 110 = NCO 101 = NCO 011 = NCO 010 = NCO 001 = NCO 000 = NCO Unimplement Unimplement	1 output is activ 1 output is activ ted: Read as 'C	e for 128 input e for 64 input e for 32 input e for 36 input e for 8 input e for 8 input e for 4 input e for 2 input e for 1 input of	t clock periods clock periods clock periods clock periods ock periods ock periods ock periods ock period			
bit 3-0	N1CKS<3:0> 1011-1111 = 1010 = LC4 1001 = LC3 1000 = LC2 0111 = LC1 0110 = CLK 0101 = SOS 0100 = MFI 0011 = MFI 0010 = LFIN 0001 = FIN	: NCO1 Clock S = Reserved _out _out _out _out XR SC NTOSC (32 kH; NTOSC (500 kH NTOSC TOSC C	Source Select z) łz)	bits			

Note 1: N1PWS applies only when operating in Pulse Frequency mode.

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE	PEIE		—			—	INTEDG	119
PIR7	_	—	NVMIF	NCO1IF	_	_	—	CWG1IF	135
PIE7	—	—	NVMIE	NCO1IE	_	_	—	CWG1IE	127
NCO1CON	N1EN	_	N1OUT	N1POL	_	_	—	N1PFM	245
NCO1CLK		N1PWS<2:0)>	—		N1CKS	<3:0>		246
NCO1ACCL				NCO1ACC<	<7:0>				247
NCO1ACCH			I	NCO1ACC<	15:8>				247
NCO1ACCU	_	_		_		NCO1ACC	<19:16>		247
NCO1INCL				NCO1INC<	7:0>				248
NCO1INCH		NCO1INC<15:8>							248
NCO1INCU	NCO1AINC<19:16>							248	
RxyPPS	—	—	_		R	xyPPS<4:0>			197

TABLE 22-1: SUMMARY OF REGISTERS ASSOCIATED WITH NCO

Legend: – = unimplemented read as '0'. Shaded cells are not used for NCO module.

23.0 COMPARATOR MODULE

Comparators are used to interface analog circuits to a digital circuit by comparing two analog voltages and providing a digital indication of their relative magnitudes. Comparators are very useful mixed signal building blocks because they provide analog functionality independent of program execution. The analog comparator module includes the following features:

- · Programmable input selection
- · Selectable voltage reference
- · Programmable output polarity
- Rising/falling output edge interrupts
- Programmable Speed/Power optimization
- CWG1 Auto-shutdown source

23.1 Comparator Overview

A single comparator is shown in Figure 23-1 along with the relationship between the analog input levels and the digital output. When the analog voltage at VIN+ is less than the analog voltage at VIN-, the output of the comparator is a digital low level. When the analog voltage at VIN+ is greater than the analog voltage at VIN-, the output of the comparator is a digital high level.

The comparators available are shown in Table 23-1.

TABLE 23-1: AVAILABLE COMPARATORS

Device	C1	C2
PIC16(L)F15354/55	•	•





24.9 Register Definitions: ZCD Control

R/W-q/q	U-0	R-x/x	R/W-0/0	U-0	U-0	R/W-0/0	R/W-0/0	
SEN	—	OUT	POL	—	—	INTP	INTN	
bit 7							bit 0	
Legend:								
R = Readable	bit	W = Writable	bit	U = Unimpler	mented bit, read	as '0'		
u = Bit is unchanged x = Bit is unknown -n/n = Value at POR and BOR/Value at all other Re								
'1' = Bit is set		'0' = Bit is cle	ared	q = value dep	ends on Config	uration bits		
bit 7	SEN: Zero-Cr	oss Detection	Enable bit					
	1 = Zero-cros	ss detect is ena	abled. ZCD pi	n is forced to o	utput to source	and sink currer	nt.	
	0 = Zero-cros	ss detect is dis	abled. ZCD pi	n operates acc	ording to PPS a	and TRIS contro	ols.	
bit 6	Unimplemen	ted: Read as '	0'					
bit 5	OUT: Zero-Cr	ross Detection	Logic Level bi	t				
	<u>POL bit = 1</u> :							
	1 = ZCD pin	is sourcing cur	rent					
	$0 = \angle CD pin$	is sinking curre	ent					
	$\frac{1 O C D R = 0}{1 = 7 C D D D R}$	is sinkina curre	ent					
	0 = ZCD pin	is sourcing cur	rent					
bit 4	POL: Zero-Cr	ross Detection	Logic Output	Polarity bit				
	1 = ZCD logi	c output is inve	rted					
	0 = ZCD logi	c output is not	inverted					
bit 3-2	Unimplemen	ted: Read as '	0'					
bit 1	INTP: Zero-C	ross Positive E	dge Interrupt	Enable bit				
	1 = ZCDIF bi	t is set on low-	to-high ZCDx	_output transiti	on			
	0 = ZCDIF bi	t is unaffected	by low-to-high	n ZCDx_output	transition			
bit 0	INTN: Zero-C	ross Negative	Edge Interrup	t Enable bit				
	1 = ZCDIF bi	t is set on high	-to-low ZCDx	_output transiti	on			
	0 = ZCDIF bi	t is unaffected	by high-to-lov	v ZCDx_output	transition			

REGISTER 24-1: ZCDCON: ZERO-CROSS DETECTION CONTROL REGISTER

TABLE 24-1: SUMMARY OF REGISTERS ASSOCIATED WITH THE ZCD MODULE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on page
PIE3	RC2IE	TX2IE	RC1IE	TX1IE	BCL2IE	SSP2IE	BCL1IE	SSP1IE	123
PIR3	RC2IF	TX2IF	RC1IF	TX1IF	BCL2IF	SSP2IF	BCL1IF	SSP1IF	131
ZCDxCON	EN	_	OUT	POL	_		INTP	INTN	265

Legend: — = unimplemented, read as '0'. Shaded cells are unused by the ZCD module.

TABLE 24-2: SUMMARY OF CONFIGURATION WORD WITH THE ZCD MODULE

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
	13:8	_	_	DEBUG	STVREN	PPS1WAY	ZCDDIS	BORV	_	76
CONFIG2	7:0	BOREN	N <1:0>	LPBOREN	_	_		PWRTE	MCLRE	

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by the ZCD module.

26.7 Timer1 Interrupts

The timer register pair (TMR1H:TMR1L) increments to FFFFh and rolls over to 0000h. When the timer rolls over, the respective timer interrupt flag bit of the PIR5 register is set. To enable the interrupt on rollover, you must set these bits:

- ON bit of the T1CON register
- TMR1IE bit of the PIE4 register
- · PEIE bit of the INTCON register
- GIE bit of the INTCON register

The interrupt is cleared by clearing the TMR1IF bit in the Interrupt Service Routine.

Note: To avoid immediate interrupt vectoring, the TMR1H:TMR1L register pair should be preloaded with a value that is not imminently about to rollover, and the TMR1IF flag should be cleared prior to enabling the timer interrupts.

26.8 Timer1 Operation During Sleep

Timer1 can only operate during Sleep when setup in Asynchronous Counter mode. In this mode, an external crystal or clock source can be used to increment the counter. To set up the timer to wake the device:

- · ON bit of the T1CON register must be set
- TMR1IE bit of the PIE4 register must be set
- PEIE bit of the INTCON register must be set
- SYNC bit of the T1CON register must be set
- CS bits of the T1CLK register must be configured
- The timer clock source must be enabled and continue operation during sleep. When the SOSC is used for this purpose, the SOSCEN bit of the OSCEN register must be set.

The device will wake-up on an overflow and execute the next instructions. If the GIE bit of the INTCON register is set, the device will call the Interrupt Service Routine.

Secondary oscillator will continue to operate in Sleep regardless of the SYNC bit setting.

26.9 CCP Capture/Compare Time Base

The CCP modules use the TMR1H:TMR1L register pair as the time base when operating in Capture or Compare mode.

In Capture mode, the value in the TMR1H:TMR1L register pair is copied into the CCPRxH:CCPRxL register pair on a configured event.

In Compare mode, an event is triggered when the value CCPRxH:CCPRxL register pair matches the value in the TMR1H:TMR1L register pair. This event can be an Auto-conversion Trigger.

The Timer1 to CCP1/2 mapping is not fixed, and can be assigned on an individual CCP module basis. All of the CCP modules may be configured to share a single Timer1 resource, or different CCP modules may be configured to use different Timer1 resources. This timer to CCP mapping selection is made in the CCPTMRS0 and CCPTMRS1 registers.

For more information, see Section 28.0 "Capture/Compare/PWM Modules".

26.10 CCP Auto-Conversion Trigger

When any of the CCP's are configured to trigger an auto-conversion, the trigger will clear the TMR1H:TMR1L register pair. This auto-conversion does not cause a timer interrupt. The CCP module may still be configured to generate a CCP interrupt.

In this mode of operation, the CCPRxH:CCPRxL register pair becomes the period register for Timer1.

The timer should be synchronized and FOSC/4 should be selected as the clock source in order to utilize the Auto-conversion Trigger. Asynchronous operation of the timer can cause an Auto-conversion Trigger to be missed.

In the event that a write to TMR1H or TMR1L coincides with an Auto-conversion Trigger from the CCP, the write will take precedence.

For more information, see Section 28.2.4 "Compare During Sleep".



REGISTER 28-4: CCPRxH REGISTER: CCPx REGISTER HIGH BYTE

| R/W-x/x |
|---------|---------|---------|---------|---------|---------|---------|---------|
| | | | CCPRx | <15:8> | | | |
| bit 7 | | | | | | | bit 0 |
| | | | | | | | |
| Logond: | | | | | | | |

Legena.		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Reset
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0
CCPxMODE = Capture mode
CCPRxH<7:0>: Captured value of TMR1H
CCPxMODE = Compare mode
CCPRxH<7:0>: MS Byte compared to TMR1H
CCPxMODE = PWM modes when CCPxFMT = 0:
CCPRxH<7:2>: Not used
CCPRxH<1:0>: Pulse-width Most Significant two bits
CCPxMODE = PWM modes when CCPxFMT = 1:
CCPRxH<7:0>: Pulse-width Most Significant eight bits

REGISTER 28-5: CCPTMRS0: CCP TIMERS CONTROL 0 REGISTER

U-0	U-0	U-0	U-0	R/W-0/0	R/W-1/1	R/W-0/0	R/W-1/1
—	—	—	—	C2TSE	EL<1:0>	C1TSE	L<1:0>
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Reset
'1' = Bit is set	'0' = Bit is cleared	

bit 7-4	Unimplemented: Read as '0'
bit 3-2	C2TSEL<1:0>: CCP2 Timer Selection 11 = CCP2 based on TMR1 (Capture/Compare) or TMR2 (PWM) 10 = CCP2 based on TMR1 (Capture/Compare) or TMR2 (PWM) 01 = CCP2 based on TMR1 (Capture/Compare) or TMR2 (PWM) 00 = Reserved
bit 1-0	C1TSEL<1:0>: CCP2 Timer Selection 11 = CCP1 based on TMR1 (Capture/Compare) or TMR2 (PWM) 10 = CCP1 based on TMR1 (Capture/Compare) or TMR2 (PWM) 01 = CCP1 based on TMR1 (Capture/Compare) or TMR2 (PWM) 00 = Reserved



FIGURE 30-1: SIMPLIFIED CWG BLOCK DIAGRAM (HALF-BRIDGE MODE)

PIC16(L)F15354/55



© 2016 Microchip Technology Inc.

FIGURE 32-9:	SPI N	IODE W	/AVEFO	RM (SL	AVE MC	DE WIT	HCKE	= 0)			
	· · ·						- 				
	· · · ·		: 		, ,		: 		> 		: : : : :
990-990 to 5399-28849 Moleci			2 2 2 2 4 4 4 4 5 5 5 5 5 5 5 5 5 5 5 5	· · · · · / · · · · · · ·	· • • • • • •		2 2 2. 2. 2. 2. 2. 2. 2. 2. 2. 2. 2. 2	e 	· • • • • • •	: : : :	· · · ·
881XC)		4. 62.1 		, 2.,		. ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~	/~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~	, / S., 1953 (.). 	:/~ ; ; ;/////////////////////////	. 66332	······································
inori Sarripie		1985 7 						. <i>44</i> -		20 2.	
SSPAF Interrupa Plac	· · · · · · · · · · · · · · · · · · ·		s s s s	6 6 5 6 	2 2 2 2 3	: : : :	s c v v		2 2 2 2 2 	· · · · · · · · · · · · · · · · · · ·	
	• . • . • .		2 2 2	, , ,	, , ,		2 2 2	- 5 5 7	\$ \$ \$		
Valie Collision describe active					,						

FIGURE 32-10: SPI MODE WAVEFORM (SLAVE MODE WITH CKE = 1)



33.3 EUSART Baud Rate Generator (BRG)

The Baud Rate Generator (BRG) is an 8-bit or 16-bit timer that is dedicated to the support of both the asynchronous and synchronous EUSART operation. By default, the BRG operates in 8-bit mode. Setting the BRG16 bit of the BAUDxCON register selects 16-bit mode.

The SPxBRGH, SPxBRGL register pair determines the period of the free running baud rate timer. In Asynchronous mode the multiplier of the baud rate period is determined by both the BRGH bit of the TXxSTA register and the BRG16 bit of the BAUDxCON register. In Synchronous mode, the BRGH bit is ignored.

Table 33-1 contains the formulas for determining the baud rate. Example 33-1 provides a sample calculation for determining the baud rate and baud rate error.

Typical baud rates and error values for various Asynchronous modes have been computed for your convenience and are shown in Table 33-3. It may be advantageous to use the high baud rate (BRGH = 1), or the 16-bit BRG (BRG16 = 1) to reduce the baud rate error. The 16-bit BRG mode is used to achieve slow baud rates for fast oscillator frequencies.

Writing a new value to the SPxBRGH, SPxBRGL register pair causes the BRG timer to be reset (or cleared). This ensures that the BRG does not wait for a timer overflow before outputting the new baud rate.

If the system clock is changed during an active receive operation, a receive error or data loss may result. To avoid this problem, check the status of the RCIDL bit to make sure that the receive operation is idle before changing the system clock.

EXAMPLE 33-1: CALCULATING BAUD RATE ERROR

For a device with Fosc of 16 MHz, desired baud rate of 9600, Asynchronous mode, 8-bit BRG:

Desired Baud Rate = $\frac{FOSC}{64([SPBRGH:SPBRGL] + 1)}$

Solving for SPxBRGH:SPxBRGL:

$X = \frac{Fosc}{\frac{Desired Baud Rate}{64} - 1}$
$=\frac{\frac{16000000}{9600}}{64}-1$
= [25.042] = 25
Calculated Baud Rate = $\frac{16000000}{64(25+1)}$
= 9615
Error = $\frac{Calc. Baud Rate - Desired Baud Rate}{Desired Baud Rate}$
$=\frac{(9615-9600)}{9600} = 0.16\%$

REGISTER 3	4-2: CLKR	CLK: CLOCK	REFERENC	CE CLOCK S	ELECTION R	EGISTER		
U-0	U-0	U-0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	
—	_	_	—	CLKRCLK<3:0>				
bit 7							bit 0	
Legend:								
R = Readable	bit	W = Writable	bit	U = Unimplen	nented bit, read	d as '0'		
u = Bit is unch	anged	x = Bit is unkr	iown	-n/n = Value a	at POR and BC	R/Value at all o	other Resets	
'1' = Bit is set		'0' = Bit is clea	ared					
bit 7-4	Unimplemen	ted: Read as '	כי					
bit 3-0	CLKRCLK<3	:0>: CLKR Inp	ut bits					
	Clock Selection	on						
	1111 = Reser	rved						
	•							
	•							
	•							
	1011 = Reser	rved						
	1010 = LC4_0	out						
	1001 = LC3_0	out						
	$1000 = LC2_0$	out						
	0111 = LC1_0	out						
	0110 = NCO	output						
	0101 = SOSC	; TOOO (04 OF L						
	0100 = MFIN	TOSC (31.25 k	(HZ)					
	0011 = MFIN	1050 (500 KH	Z)					
	0010 = LFINI							
	0001 = FIN	1030						
	0000 - FOSC							

TABLE 34-1: SUMMARY OF REGISTERS ASSOCIATED WITH CLOCK REFERENCE OUTPUT

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
CLKRCON	CLKREN	_	_	CLKRD	C<1:0> CLKRDIV<2:0>			452	
CLKRCLK	_	_	_	_	CLKRCLK<3:0>				453
CLCxSELy	—			LCxDyS<5:0>					363
RxyPPS	_	_	_	RxyPPS<4:0>					197

Legend: — = unimplemented, read as '0'. Shaded cells are not used by the CLKR module.

RETLW	Return with literal in W				
Syntax:	[<i>label</i>] RETLW k				
Operands:	$0 \le k \le 255$				
Operation:	$k \rightarrow (W);$ TOS \rightarrow PC				
Status Affected:	None				
Description:	The W register is loaded with the 8-bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a 2-cycle instruction.				
Words:	1				
Cycles:	2				
Example:	CALL TABLE;W contains table ;offset value • ;W now has table value				
TABLE	• • ADDWF PC ;W = offset RETLW k1 ;Begin table RETLW k2 ; • • • RETLW kn ; End of table				
	Before Instruction				
	vv = 0x07				

After Instruction

[label] RETURN

None

None

 $\mathsf{TOS}\to\mathsf{PC}$

RETURN

Operands:

Operation:

Description:

Status Affected:

Syntax:

W =

Return from Subroutine

Return from subroutine. The stack is POPed and the top of the stack (TOS) is loaded into the program counter. This is a 2-cycle instruction.

value of k8

RLF	Rotate Left f through Carry						
Syntax:	[<i>label</i>] RLF f,d						
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$						
Operation:	See description below						
Status Affected:	С						
Description:	The contents of register 'f' are rotated one bit to the left through the Carry flag. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is stored back in register 'f'.						
Words:	1						
Cycles:	1						
Example:	RLF REG1,0						
	Before Instruction						
	REG1 = 1110 0110						
	C = 0						
	After Instruction						
	REG1 = 1110 0110						
	$W = 1100 \ 1100$						
	C = 1						
RRF	Rotate Right f through Carry						

Syntax:	[<i>label</i>] RRF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	See description below
Status Affected:	С
Description:	The contents of register 'f' are rotated one bit to the right through the Carry flag. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.

		_
┍╼╸С	Register f	

37.3 DC Characteristics

TABLE 37-1: SUPPLY VOLTAGE							
PIC16LF15354/55			Standard Operating Conditions (unless otherwise stated)				
PIC16F15354/55							
Sym.	Characteristic	Min.	Тур.†	Max.	Units	Conditions	
Supply Voltage							
Vdd		1.8 2.5		3.6 3.6	V ⊁∕	Fosc ≥ 16 MHz Fosc > 16 MH 2	
Vdd		2.3 2.5		5.5 5.5	₹V V	Fosc ≤ 16 MHz Føsc ≥ 16 MHz	
RAM Data Retention ⁽¹⁾							
Vdr		1.5	_	$\langle \downarrow \rangle$	V \	Device in Sleep mode	
Vdr		1.7	-~		Y	Device in Sleep mode	
Power-on Reset Release Voltage ⁽²⁾							
VPOR		—	/1,6	\checkmark	V	BOR or LPBOR disabled ⁽³⁾	
VPOR			1.6	Á	> V	BOR or LPBOR disabled ⁽³⁾	
Power-on Reset Rearm Voltage ⁽²⁾							
VPORR		$\neq /$	8.0	\searrow	V	BOR or LPBOR disabled ⁽³⁾	
VPORR	\frown	$\sim \sim$	1,5	> -	V	BOR or LPBOR disabled ⁽³⁾	
VDD Rise Rate to ensure internal Power-on Reset signal ⁽²⁾							
SVDD		0.05	\searrow	—	V/ms	BOR or LPBOR disabled ⁽³⁾	
SVDD		0.05	> _	_	V/ms	BOR or LPBOR disabled ⁽³⁾	
	37-1: 3 37-1: 3 5354/55 Sym. 5354/55 Sym. Voltage VDD VDD VDD ta Retent VDR VDR VDR VDR VDR VDR VDR VDR VDR VPOR VPOR VPORR VPORR SVDD SVDD	37-1: SUPPLY VOLTAGE 37-1: SUPPLY VOLTAGE 15354/55 5354/55 Sym. Characteristic Voltage VDD VDD VDD VDD VDD VDR VDR VDR VDR VDR VDR VDR VDR VPOR VPOR VPOR VPOR VPORR VPORR VPORR VPORR SVDD SVDD	Sym. Characteristic Min. 5354/55 Standard 5354/55 Min. Voltage No. VDD 1.8 2.5 2.3 VDD 2.3 VDD 1.5 VDR 1.5 VDR 1.7 on Reset Release Voltage ⁽²⁾	Sym. Characteristic Min. Typ.† Sym. Characteristic Min. Typ.† Voltage 1.8 – VDD 1.8 – VDD 2.5 – VDD 2.5 – VDD 2.5 – VDD 2.5 – VDD 1.5 – VDR 1.7 – On Reset Release Voltage ⁽²⁾ VPOR – VPOR – 1.6 VPOR – 1.6 VPOR – 1.5 VPOR – 1.6 VPOR – 1.6 VPOR – 1.5 VPOR – 1.5 SVDD 0.05 –	Supply voltage Sym. Characteristic Min. Typ.† Max. Voltage Voltage XVD 1.8 – 3.6 VDD 1.8 – 3.6 2.5 – 3.6 VDD 2.3 – 5.5 2.5 – 5.5 VDD 2.3 – 5.5 2.5 – 5.5 VDR 1.5 – 9.5 1.7 – – 9.5 VDR 1.7 – – 1.6 – 9.5 2.5 – 1.6 – 9.8 – 9.8 – 9.8 – 9.8 – 9.8 – 9.8 – 9.8 – 9.8 – 9.8 – 9.8 – 9.8 – 9.8 – 9.8 – 9.8 – 9.8 – – 9.8 – – 9.8 – – 9.8 – – <	Bo Characteristics 37-1: SUPPLY VOLTAGE Standard Operating Conditions IS354/55 Sym. Characteristic Min. Typ.† Max. Units Voltage VDD 1.8 – 3.6 V VDD 1.8 – 3.6 V VDD 2.5 – 3.6 V VDD 2.5 – 5.5 V VDD 2.5 – 5.5 V VDR 1.5 – V VDR 1.7 – V VDR 1.7 – V VDR 1.6 V VPOR – 1.6 V VPOR – 1.6 V VPOR – 1.5 – V On Reset Rearm Voltage ⁽²⁾ V V V V V SVDD 0.05 – V/ms V V V VPORR – V/ms V V – V/m	

† Data in "Typ." column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

2: See Figure 37-3, POR and POR REARM with Slow Rising VDD.

3: Please see Table 37-11 for BØR and LPBOR trip point information.

4: = LF device